## What is claimed is:

1. A semiconductor package comprising:

a substrate including a redundant bond finger, an added bond finger connected to a redundant solder ball pad;

a semiconductor chip having an added bond pad attached to the substrate;

a normal wire bonding unit coupled between the added bond pad and the redundant bond finger; and

an added wire bonding unit coupled between the redundant bond finger and the added bond finger.

- The semiconductor package of claim 1, further comprising:

   an encapsulant for encapsulating the semiconductor chip, the normal and added wire
   bonding units.
  - 3. The semiconductor package of claim 2, further comprising: a solder ball connected to the redundant solder ball pad.
- 4. The semiconductor/package of claim 1, wherein the substrate is a single-layer substrate on which a printed circuit pattern is formed.
- 5. The semiconductor package of claim 1, wherein the substrate is a double-layer substrate or a multi-layer substrate.
- 25 6. The semiconductor package of claim 1, wherein a solder mask is not formed on the added bond finger.
  - 7. The semiconductor package of claim 1, wherein the added wire bonding unit is formed over the substrate.
  - 8. The semiconductor package of claim 1, wherein the added wire bonding unit is formed on an outer region of the substrate on which the semiconductor chip is mounted.

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- 9. The semiconductor package of claim 1, wherein the added wire bonding unit is one unit or a plurality of units.
- 10. The semiconductor package of claim 1, wherein the semiconductor chip is attached to the substrate using an adhesive.
  - 11: The semiconductor package of claim 1, wherein the added bond finger is made by further extending the printed circuit pattern on the substitute.
  - 12. The semiconductor package of claim 1, wherein the added bond finger has the same pad shape as that of the redundant bond finger.
  - 13. A semiconductor package comprising:

    a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad;
    a semiconductor chip attached to the substrate; and
    an added wire bonding unit coupled between the first printed circuit pattern to the second printed circuit pattern.
  - 14. The semiconductor package of claim 13, further comprising: an encapsulant for encapsulating the semiconductor chip and the added wire bonding unit.
    - 15. The semiconductor package of claim 14, further comprising: a solder ball connected to the redundant solder ball pad.
  - 16. The semiconductor package of claim 13, wherein the first and second printed circuit patterns each have a width that enables wire bonding to be performed thereon.
- 30 17. A method for marryfacturing a semiconductor package, the method comprising:

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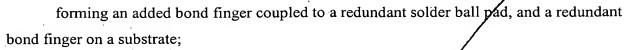
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attaching a semiconductor chip having an added bond pad to the substrate; forming a normal wire bonding unit coupled between the added bond pad to the

redundant bond finger; and

forming an added wire bonding unit coupled between the redundant bond finger to the added bond finger.

- 18. The method of claim 17, further comprising:
  encapsulating the semiconductor chip, the normal wire bonding unit, and the added wire bonding unit.
  - 19. The method of claim 18, further comprising: attaching a solder ball to a solder ball pad including the redundant solder ball pad.
- 20. The method of claim/17, wherein the substrate is a single-layer substrate, a double-layer substrate, or a multi-layer substrate.
- 21. The method of claim 17, wherein the added wire bonding is performed on an outer region of the substrate on which the semiconductor chip is attached.
- 22. The method of claim 17, wherein a single added wire bonding unit or a plurality of added wire bonding units are formed during performing the added wire bonding.
- 23. A method for manufacturing a semiconductor package, the method comprising:

preparing a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad; attaching a semiconductor chip to the substrate; and

forming an added wire bonding unit coupled between the first printed circuit pattern and the second printed circuit pattern.

- 24. The method of claim 23, further comprising: encapsulating the semiconductor chip and the added wire bonding unit.
- 25. The method of claim 24, further comprising: attaching a solder ball to a solder ball pad including the redundant solder ball pad.